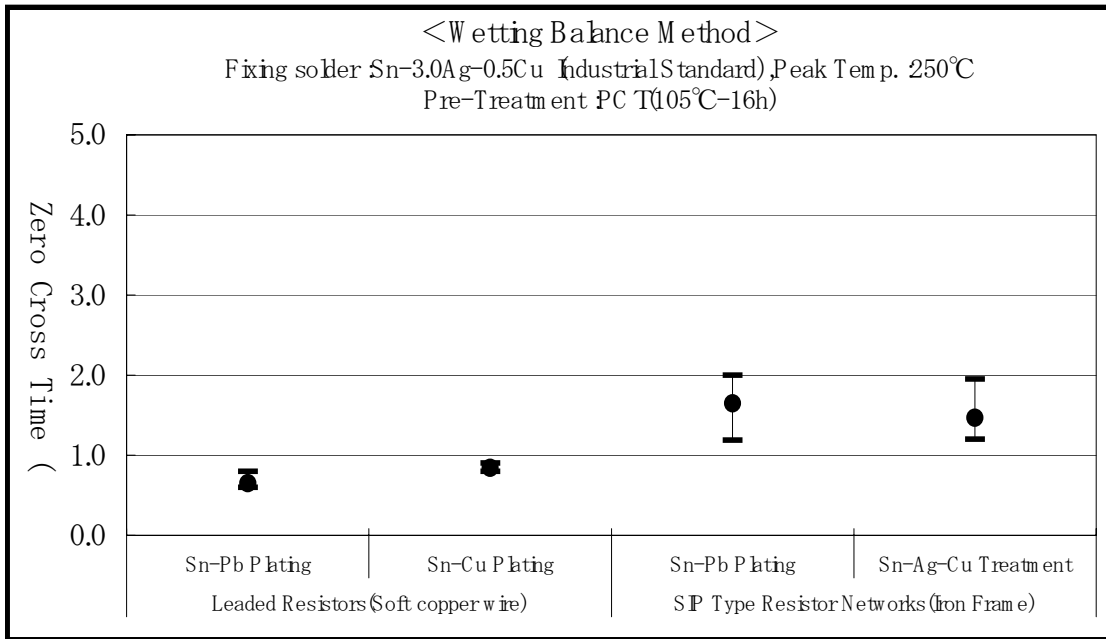


Section 1 – All tests in Section 1 used Pb-free Solder Paste for Testing to Prove Compatibility of the Pb-Free Components vs. Pb-Free Solder Paste. The Pb-Free Solder Paste used was Sn-3Ag-0.5Cu Solder.

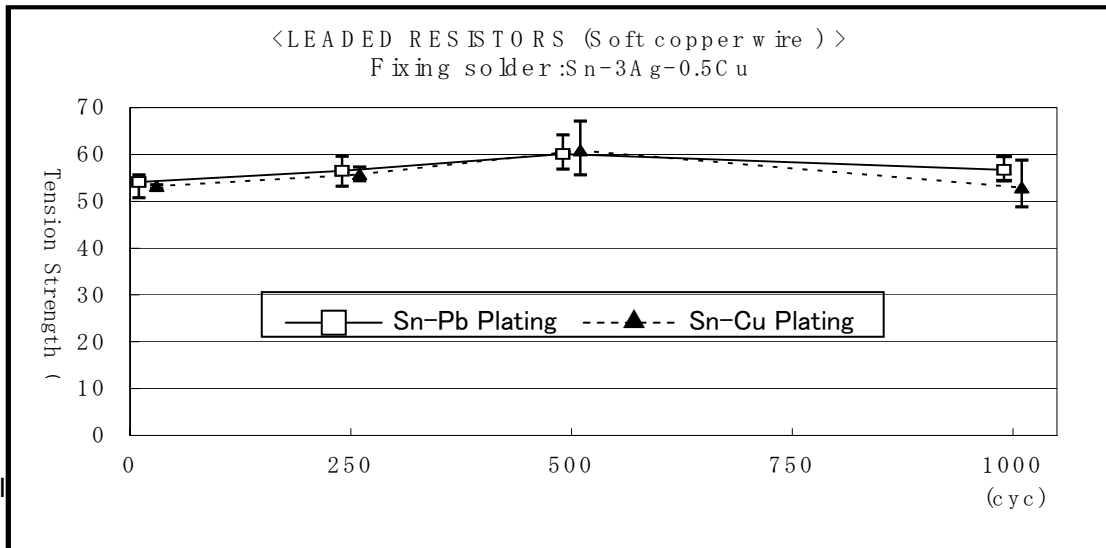
(1) Solder Wetting – Wetting Balance of Through Hole Components with Sn-3Ag-0.5Cu Solder



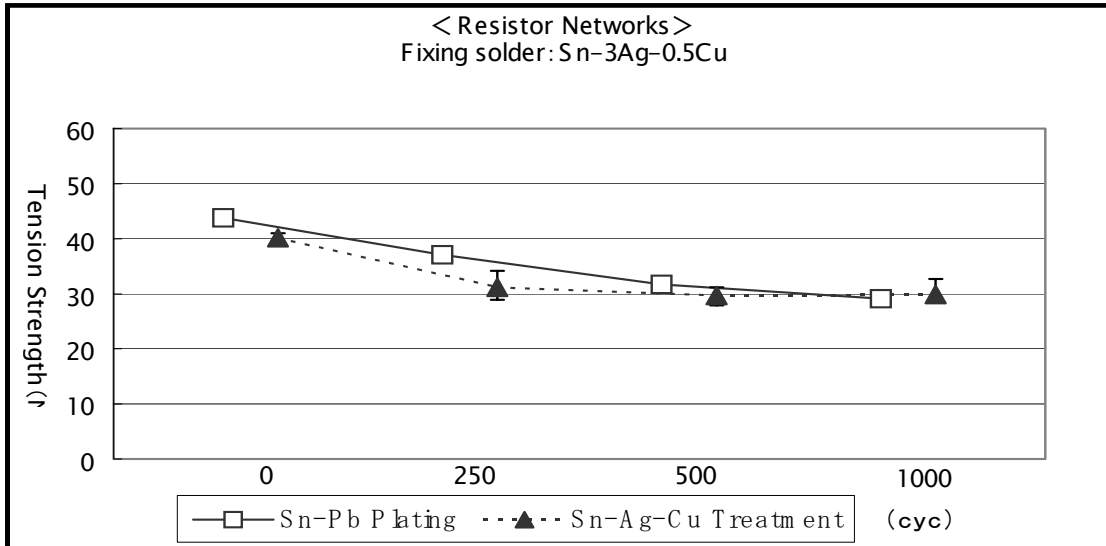
(2) Joining Strength

Test Conditions : Temperature cycling of -55C (30min.) / +125C (30min.)

Joining Strength of Lead Wire Type

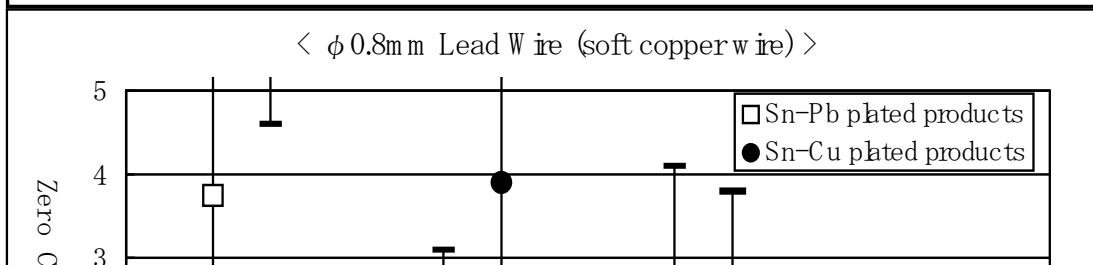
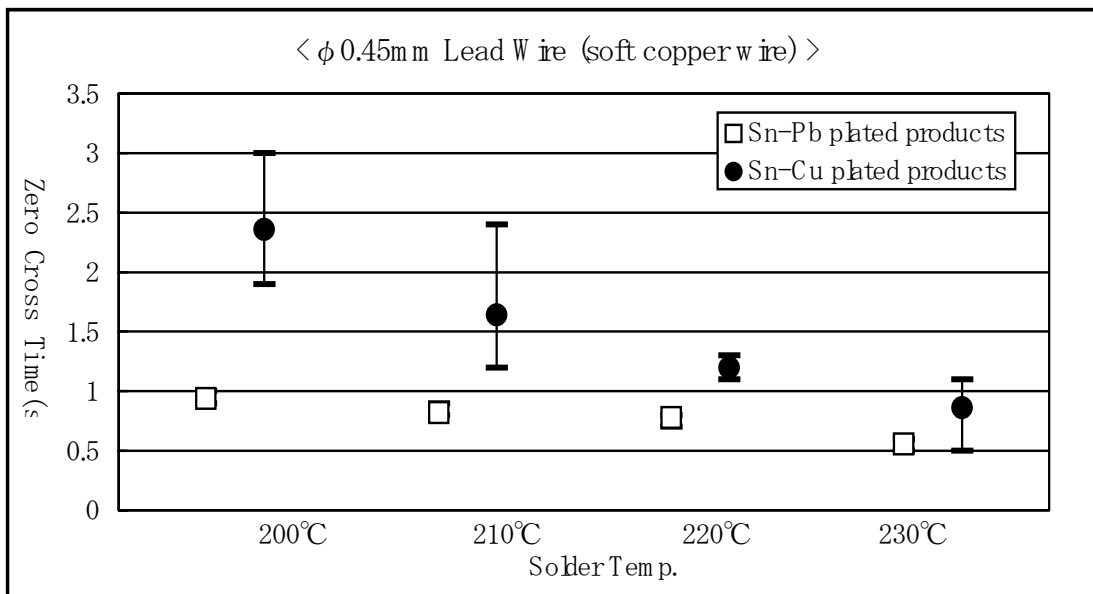


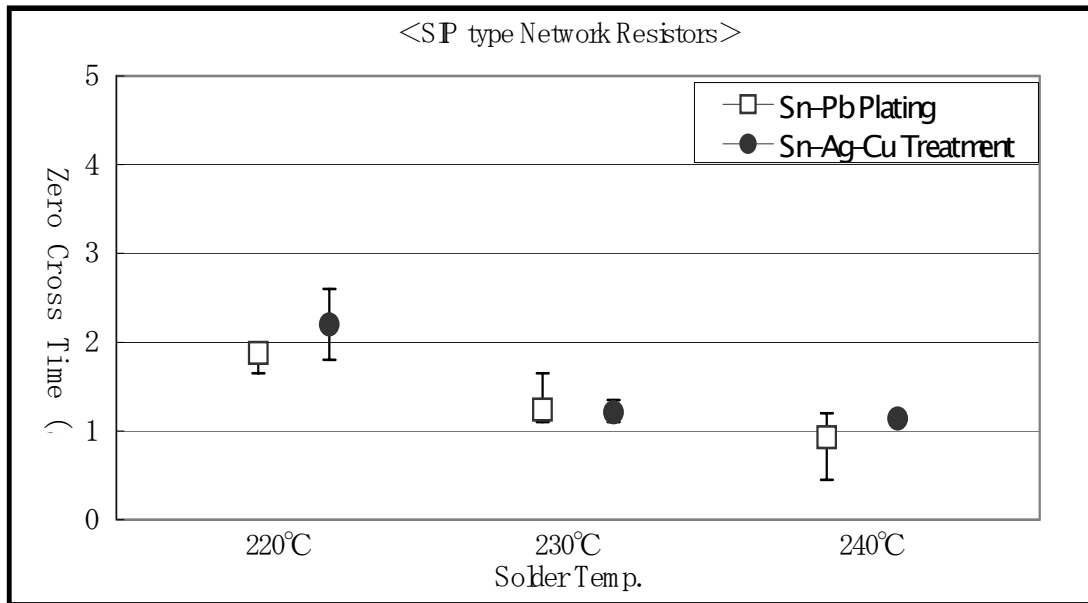
3. SI



Section 2 – All tests in Section 1 used SnPb Solder Paste for Testing to Prove Compatibility of the Pb-Free Components vs. SnPb Solder Paste. The SnPb Solder Paste used was Sn-40Pb Solder.

(1) Solder Wetting – Wetting Balance of Through Hole Components with Sn-40Pb Solder

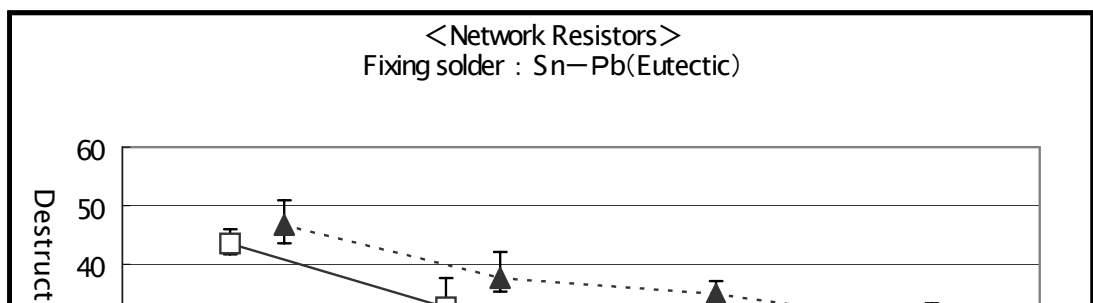
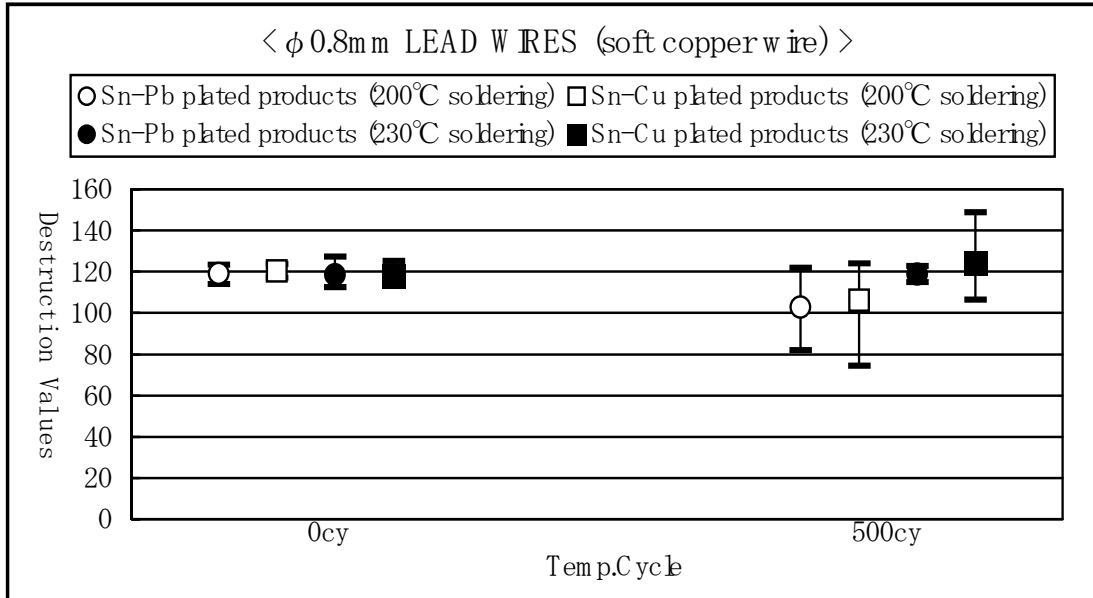
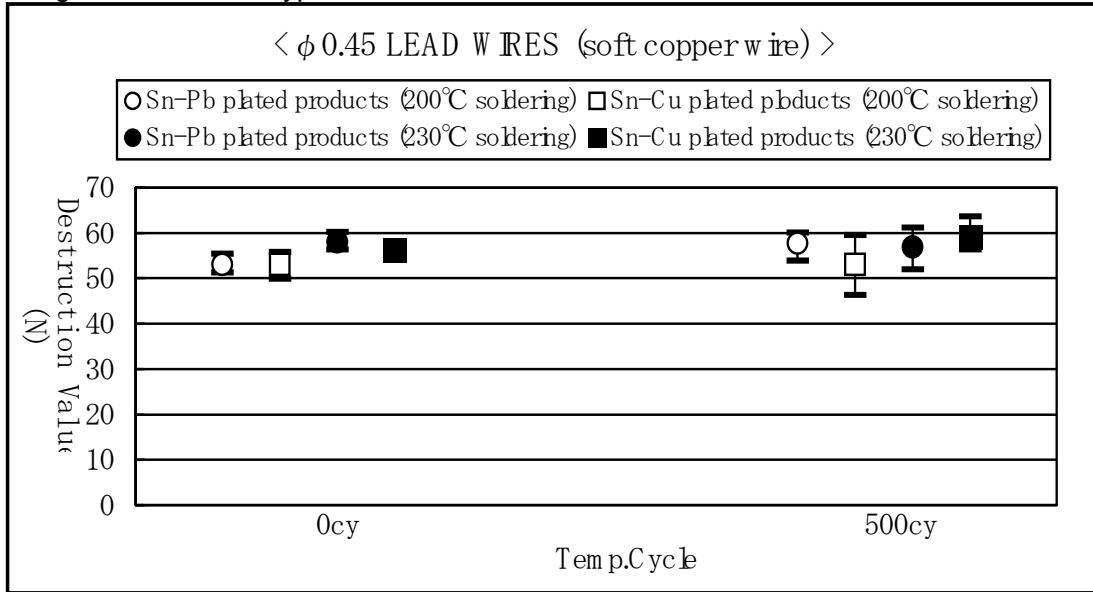




(2) Joining Strength

Test Conditions : Temperature cycling of -55C (30min.) / +125C (30min.)

Joining Strength of Lead Wire Type



(3) Terminal Connection Strength of SIP Type Network Resistors

Test Conditions : Application of Weight Toward Terminal Axis 9.8N/10sec.

